# DANAE - a new experiment for direct dark matter detection with DEPFET silicon detector

Hexi Shi HEPHY ÖAW

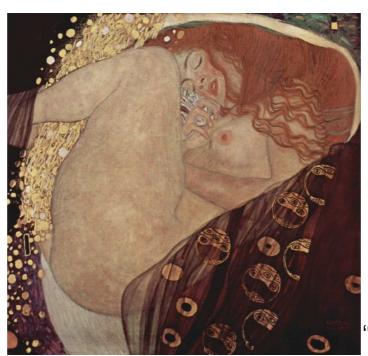




#### DANAE (DANAË)

# <u>Direct dArk matter search using DEPFET with repetitive-Non-destructive-readout Application Experiment</u>

OeAW funding for detector technology



"Danae" by G. Klimt

#### Collaboration



**Austria** 

A. Bähr <sup>A</sup>, J. Ninkovic <sup>A</sup>, J. Treis <sup>A</sup>, H. Kluck <sup>B</sup>, <sup>C</sup>, J. Schieck <sup>B</sup>, <sup>C</sup>, H. Shi <sup>B</sup>,



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## The project overview

#### Direct Dark Matter Detection with DEPFET

• minimal reach for nuclear recoil experiments 10-37

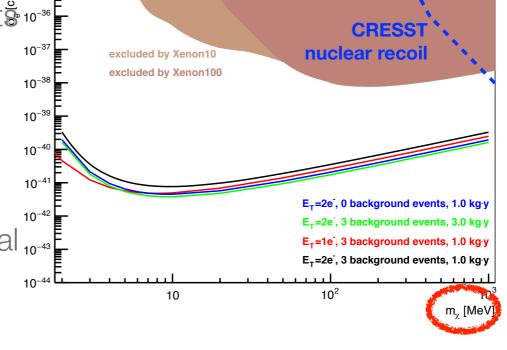
dark matter electron scattering offers
 reach towards MeV dark matter

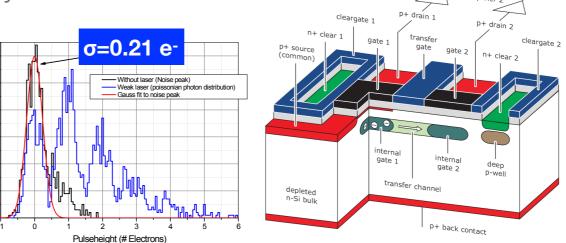
measurement of low noise ionisation signal 10-43
 in low background environment

 RNDR\*DEPFET sensors developed by semiconductor laboratory of MPG

setup for proof-of-principle
 measurement currently prepared

expect first results early 2019





EPJ C, 77(12), 279 (2017)

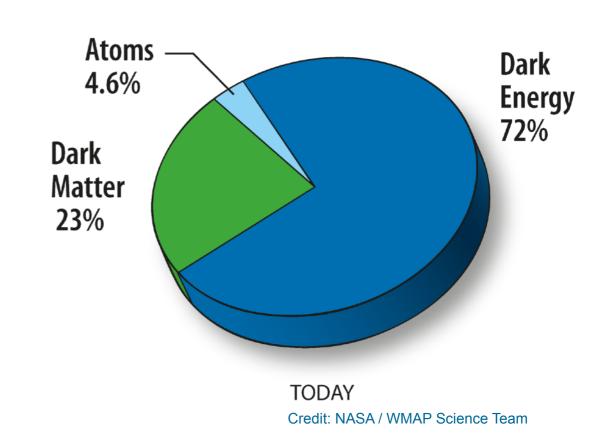
#### Dark matter landscape - partly

Over 80% of the mass in the universe is invisible dark matter

"WIMP" as a dark matter candidate:

- weakly interacting with matter  $<\sigma_{WIMP} \cdot v> \sim G_{F^2} \cdot m_{X^2} \sim 1/\Omega_X$
- fits the Hubble constant and "relic" density of dark matter

predicts dark matter WIMP mass between 2 GeV and 120 TeV





dominated the direct detection experiments until recently

#### WIMP direct detection method

look for nuclear recoils from WIMP-nucleus scattering

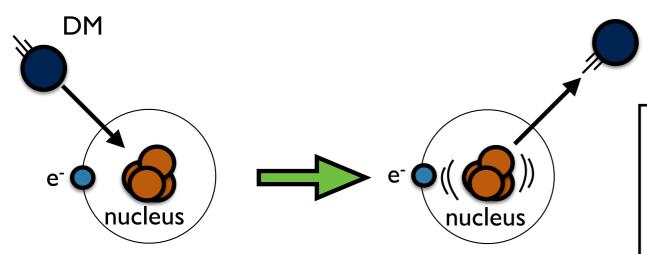


image credit R. Essig

Energy deposit in target material in forms of :

- light
- phonon
- electric charge

DM

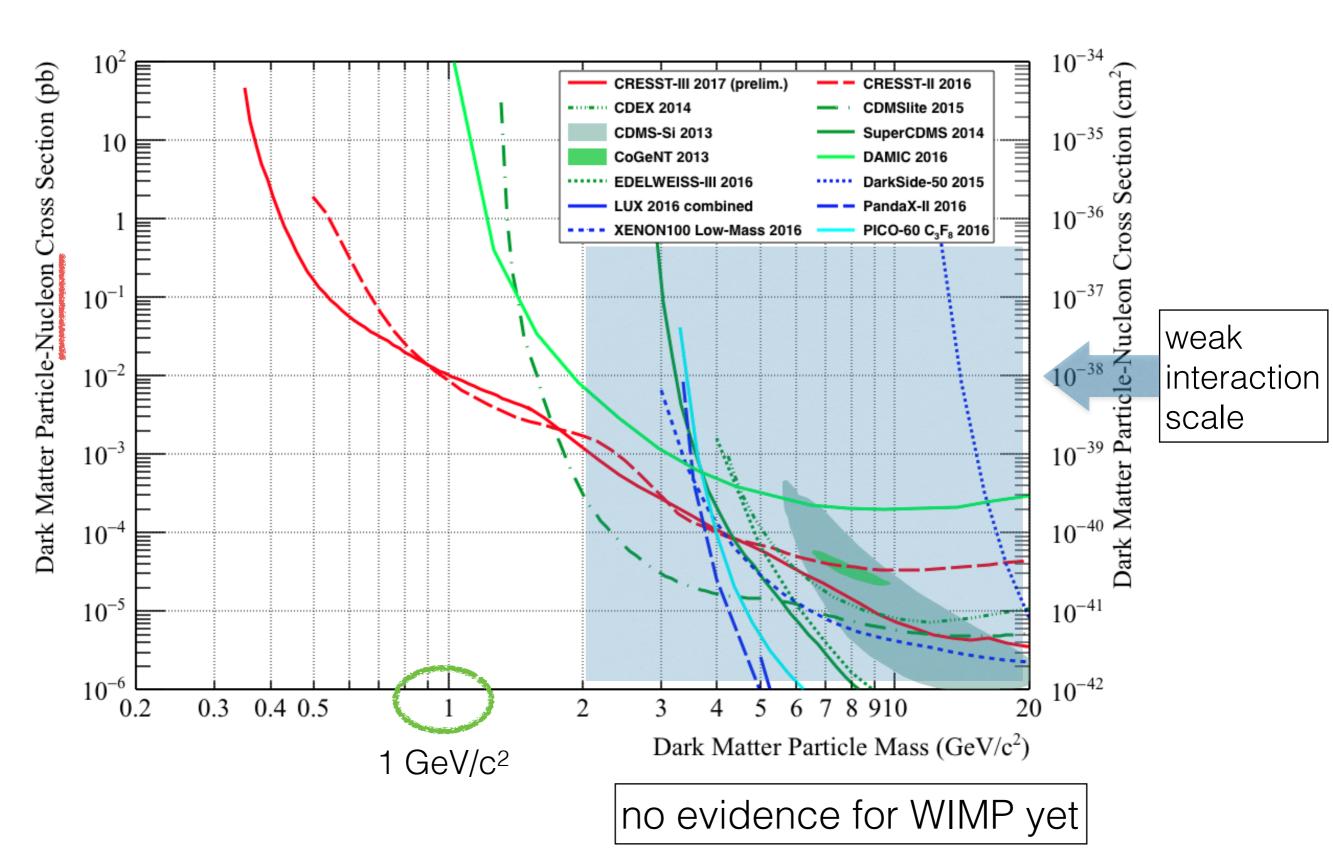
Detection limitation : energy deposit from nucleus recoil  $E_{NR} \sim 2\mu_{X,N}^2 \cdot v_X/m_N$ 

-> for 100 MeV  $m_X$ ,  $E_{NR} \sim 1 \text{ eV} *$ 

plus quenching factors and noise level of the detectors

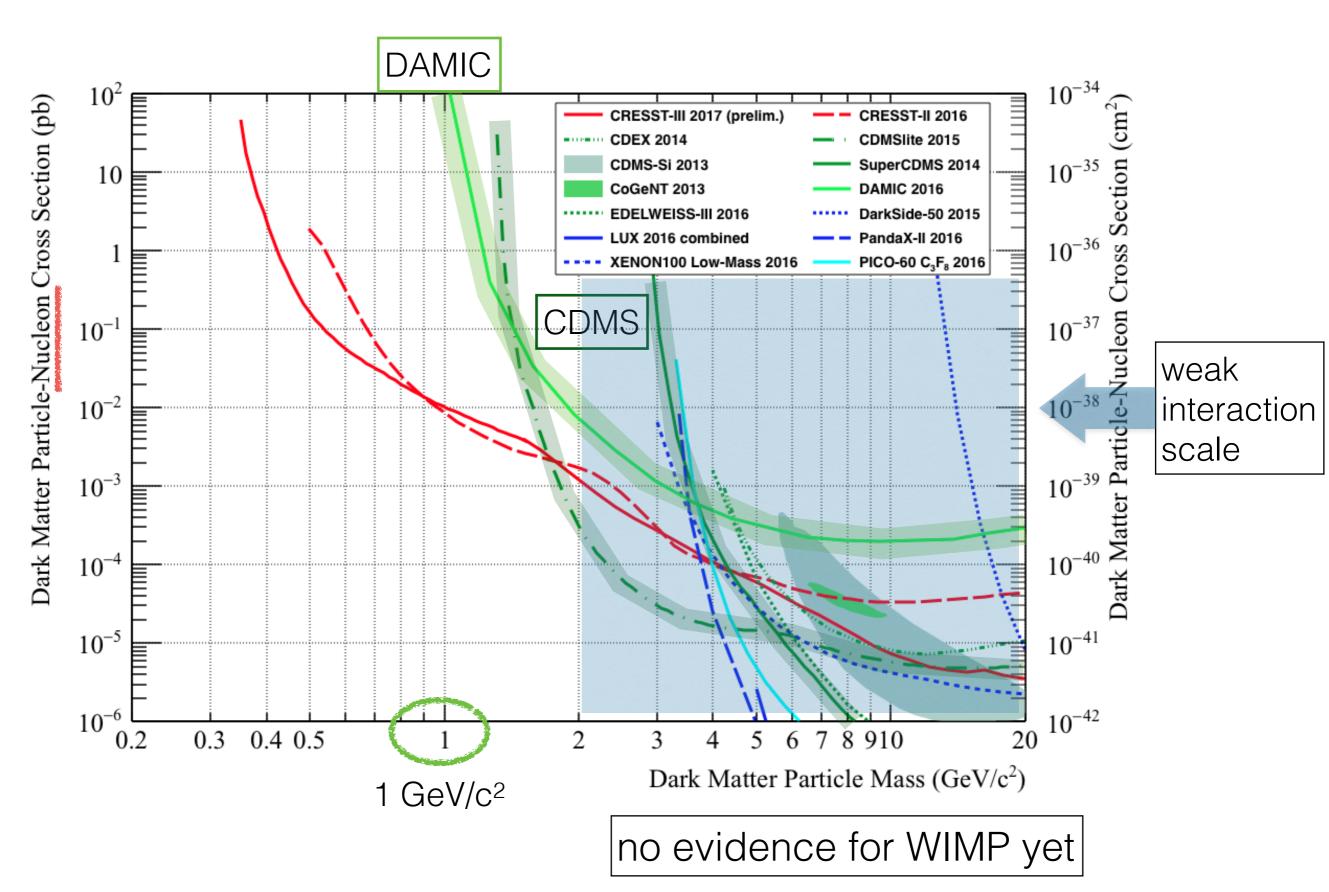
typical DM velocity  $v_{\rm X} \lesssim 800~{\rm km/s}$  \*for silicon

#### DM-nucleus scattering direct search status



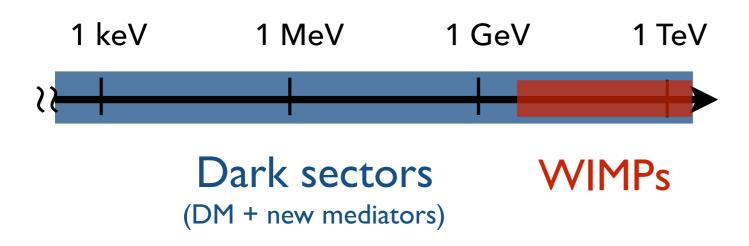
arXiv:1711.07692

#### DM-nucleus scattering direct search status

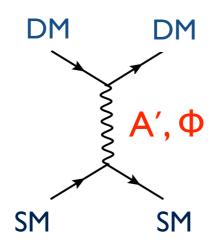


arXiv:1711.07692

#### **Dark Sector and Light Dark Matter**



several sharp "theory" targets
(freeze-out, asymmetric, freeze-in, SIMP, ELDER)



DM scattering

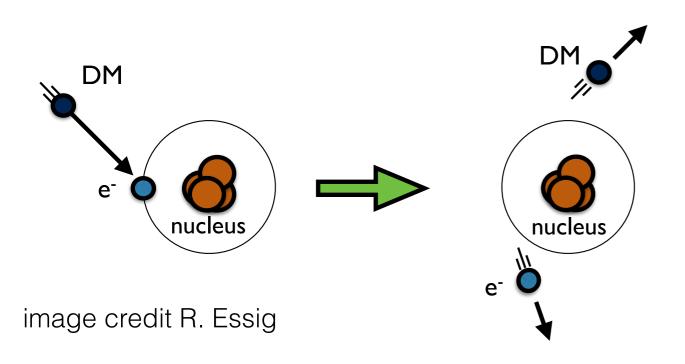
image credit R. Essig

Dark sector:

interaction between DM and standard model particle mediated by a dark photon (one example of mediators)

clear predictions from multiple models over wide DM mass region, including **keV ~ GeV**-> comparable observables in experiments

# **DM-electron scattering**



#### kinematically

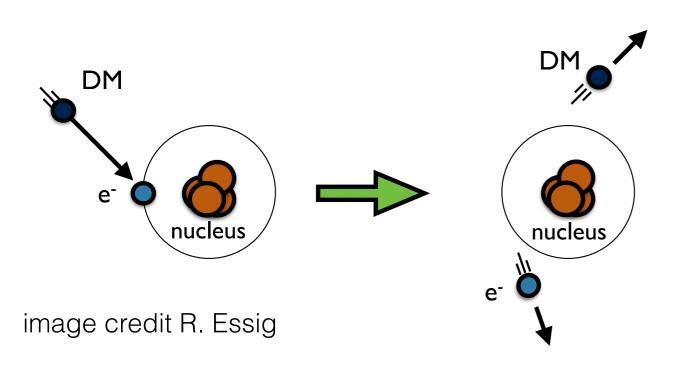
to overcome binding energy  $\Delta E$ 

need 
$$E_{\mathrm{DM}} \sim \frac{1}{2} \, m_{\mathrm{DM}} \, v_{\mathrm{DM}}^2 > \Delta E$$

$$v_{\rm DM} \lesssim 800 \ {\rm km/s} \implies \boxed{m_{\rm DM} \gtrsim 300 \ {\rm keV} \ \left(\frac{\Delta E}{1 \ {\rm eV}}\right)}$$

O(100 keV)

# **DM-electron scattering**



#### kinematically

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O(100 keV)

bound e- does not have definite momentum, typical momentum transfer is set by e- not by DM.

$$q_{\rm typ} \sim \alpha m_e \sim 4 \ {\rm keV}$$

(for outer shell electron)

transferred energy:  $\Delta E_e \sim \vec{q} \cdot \vec{v}_{\rm DM}$ 

$$\Delta E_e \sim 4 \text{ eV}$$

typical recoil energy

JHEP05(2016)046

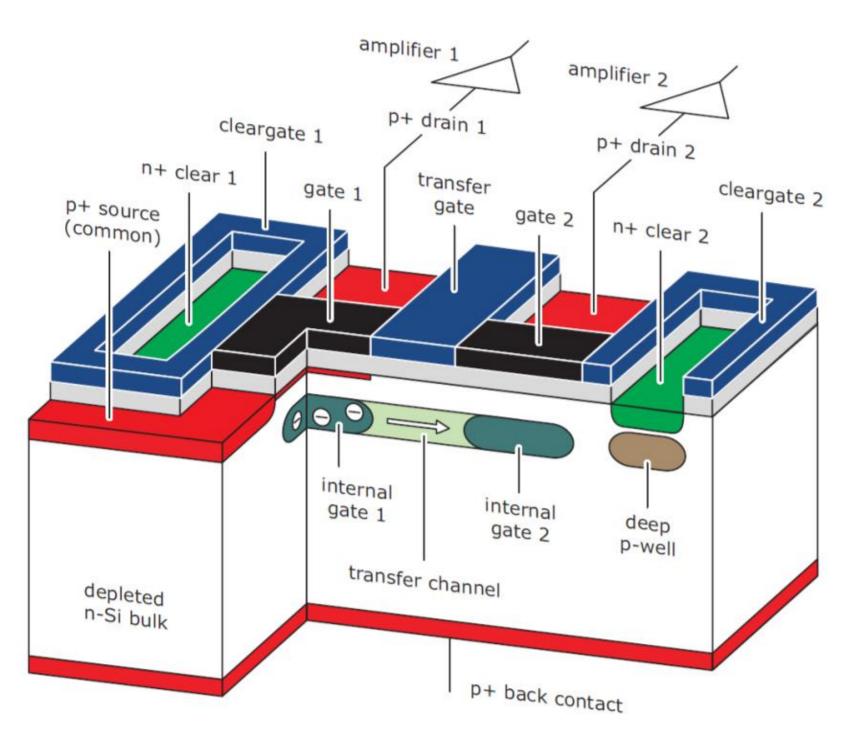
# Target materials for electron recoils

Target Type	Examples	E <sub>th</sub>	m <sub>χ</sub> threshold	Status	Timescale
Noble liquids	Xe, Ar, He	~ 10 eV	~ 5 MeV	Done w data; improvements possible	existing
Semi- conductors	Ge, <b>Si</b>	~ 1 eV	~ 200 keV	(E <sub>th</sub> ~ 40 eV SuperCDMS, <b>DAMIC</b> ) E <sub>th</sub> ~ 1eV <b>SENSEI</b> , <b>DEPFET</b> R&D	~ 1-2 years
Scintillators	GaAs, Nal, Csl,	~ 1 eV	~ 200 keV	R&D required	≤ 5 years
Supferfluid	He	~ 1 eV	~ 1 MeV	R&D required unknown background	≲ 5 years
Super- conductor	Al	~ 1 meV	~ 1 keV	R&D required unknown background	~ 10 - 15 years

arXiv:1608.08632

structure of RNDR DEPFET "super-pixel"

RNDR readout

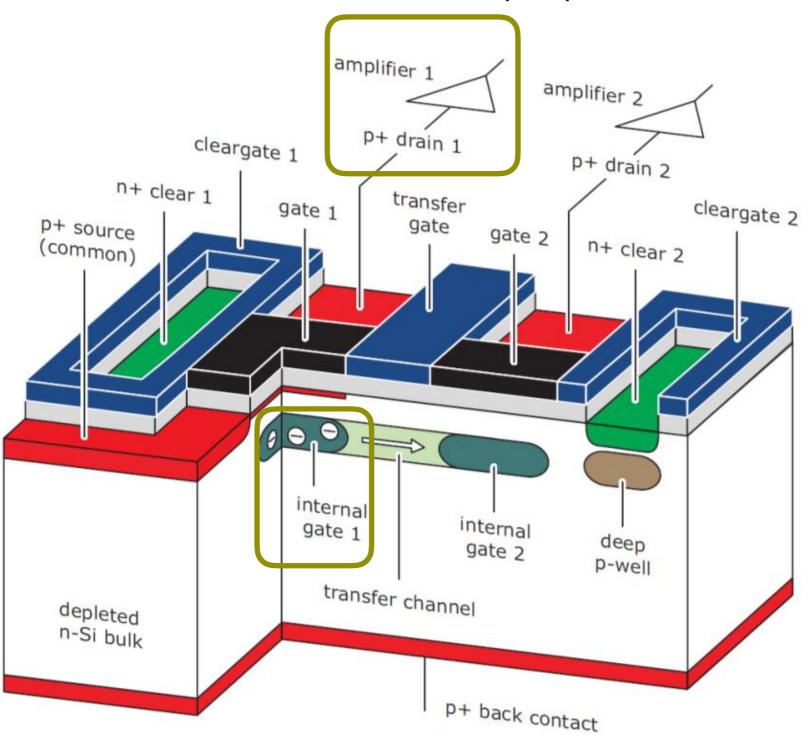


read N times *effective noise*:

#### structure of RNDR DEPFET "super-pixel"

RNDR readout

read 1: noise  $\sigma$ 



read N times *effective noise*:

structure of RNDR DEPFET "super-pixel"

amplifier 1 amplifier 2 p+ drain 1 cleargate 1 p+ drain 2 n+ clear 1 transfer gate 1 cleargate 2 p+ source gate gate 2 (common) n+ clear 2 000 internal internal gate 1 deep gate 2 p-well transfer channel depleted n-Si bulk p+ back contact

RNDR readout

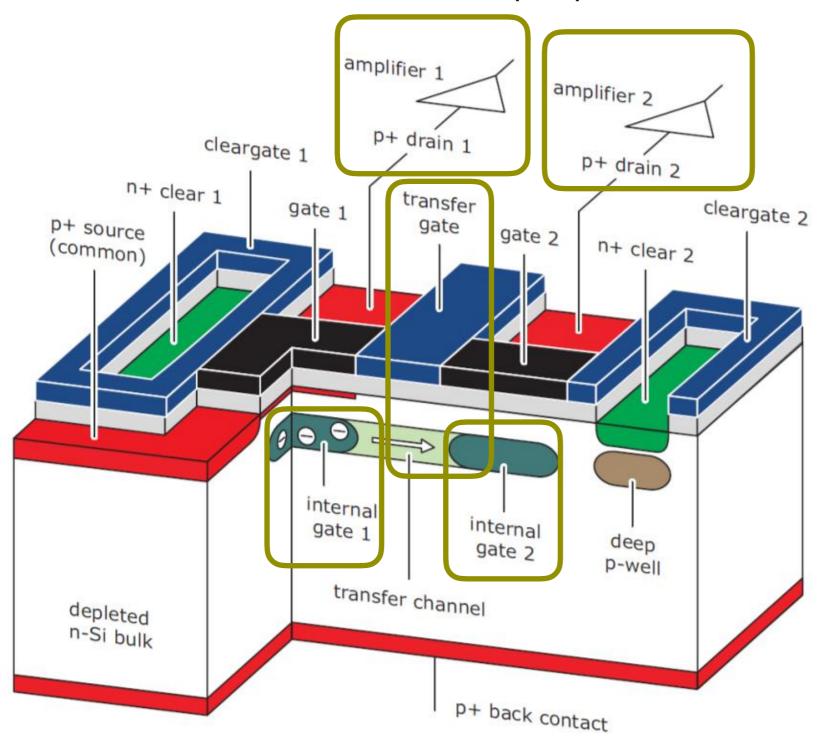
read 1: noise  $\sigma$ 



transfer gate open

read N times <u>effective noise</u>:

#### structure of RNDR DEPFET "super-pixel"



RNDR readout

read 1 : noise σ



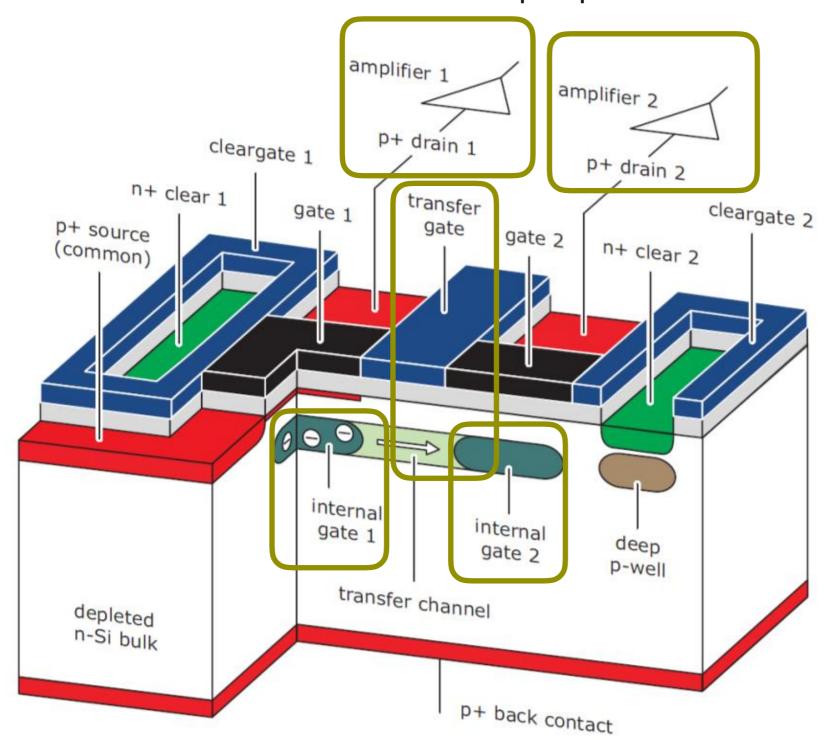
transfer gate open



read 2: noise  $\sigma$ 

read N times <u>effective noise</u>:

#### structure of RNDR DEPFET "super-pixel"



EPJ C, 77(12), 279 (2017)

RNDR readout

read 1: noise σ



transfer gate open



read 2: noise  $\sigma$ 

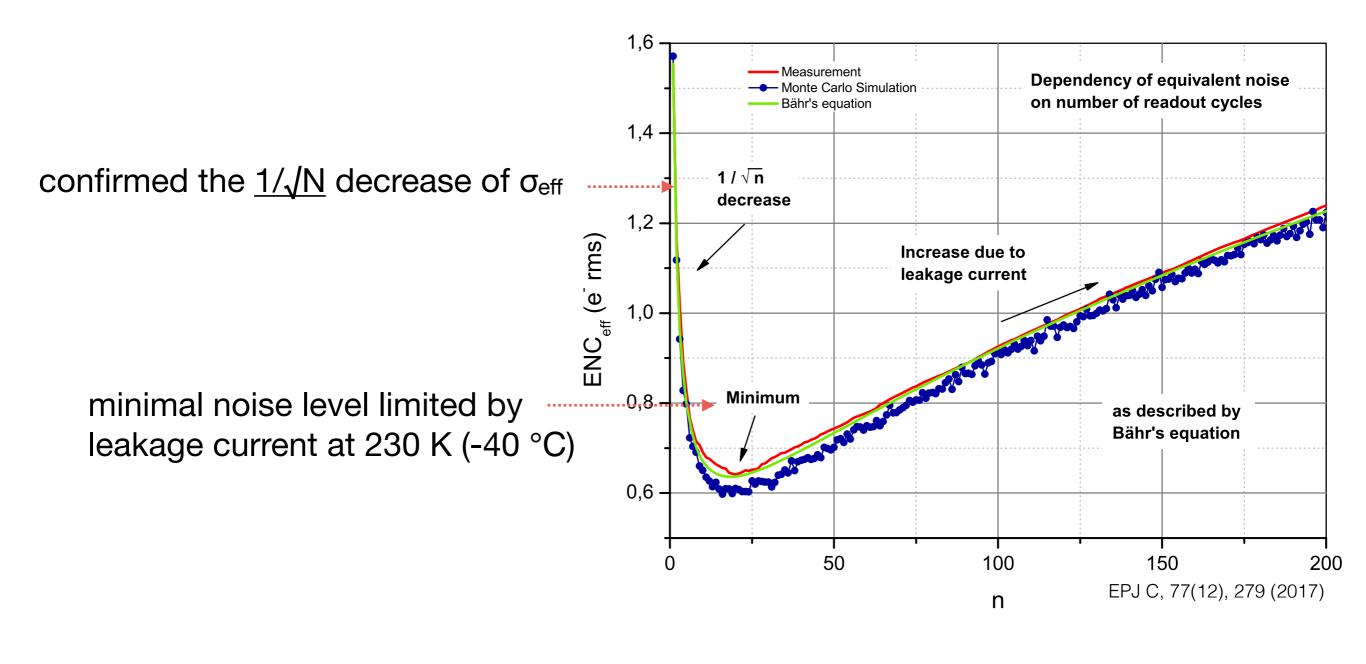
: repeat **N** times independent measurements

clear charges

read N times *effective noise*:

$$\sigma_{\rm eff} = \sigma/(\sqrt{N})$$

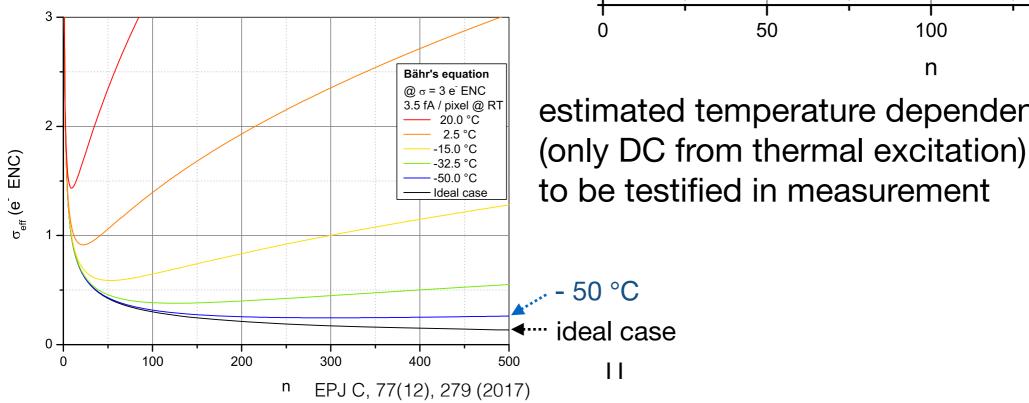
## **DEPFET RNDR single pixel performance**

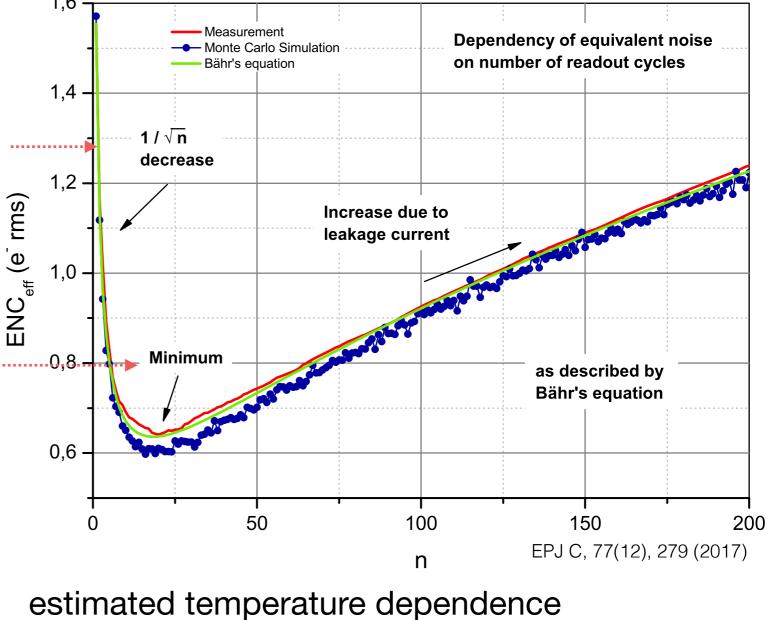


#### **DEPFET RNDR single pixel performance**

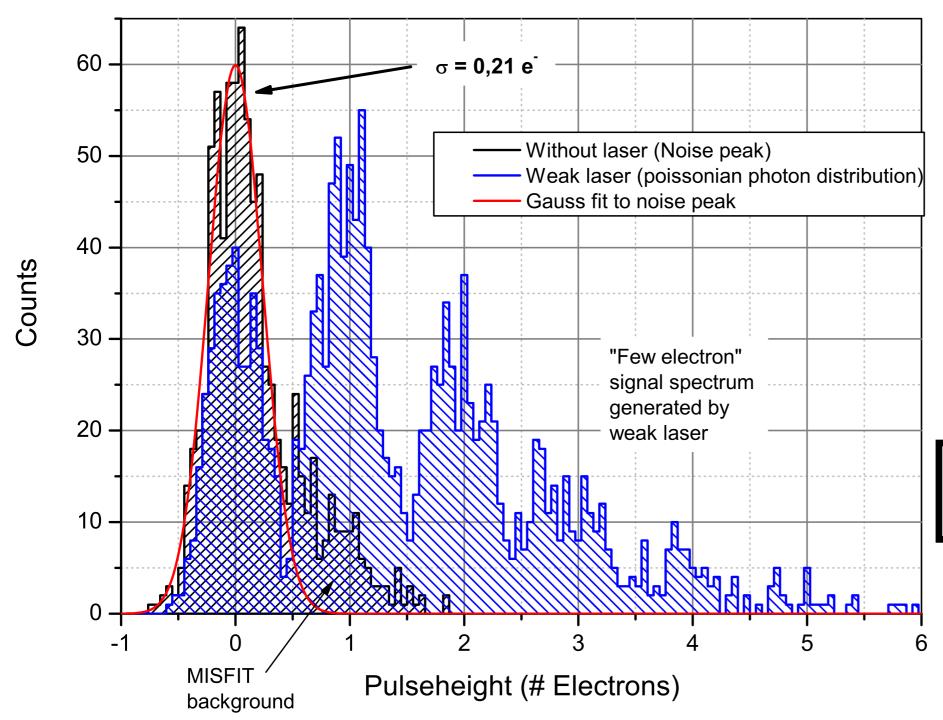
confirmed the  $1/\sqrt{N}$  decrease of  $\sigma_{eff}$ 

minimal noise level limited by leakage current at 230 K (-40 °C)





# **DEPFET RNDR single pixel performance**

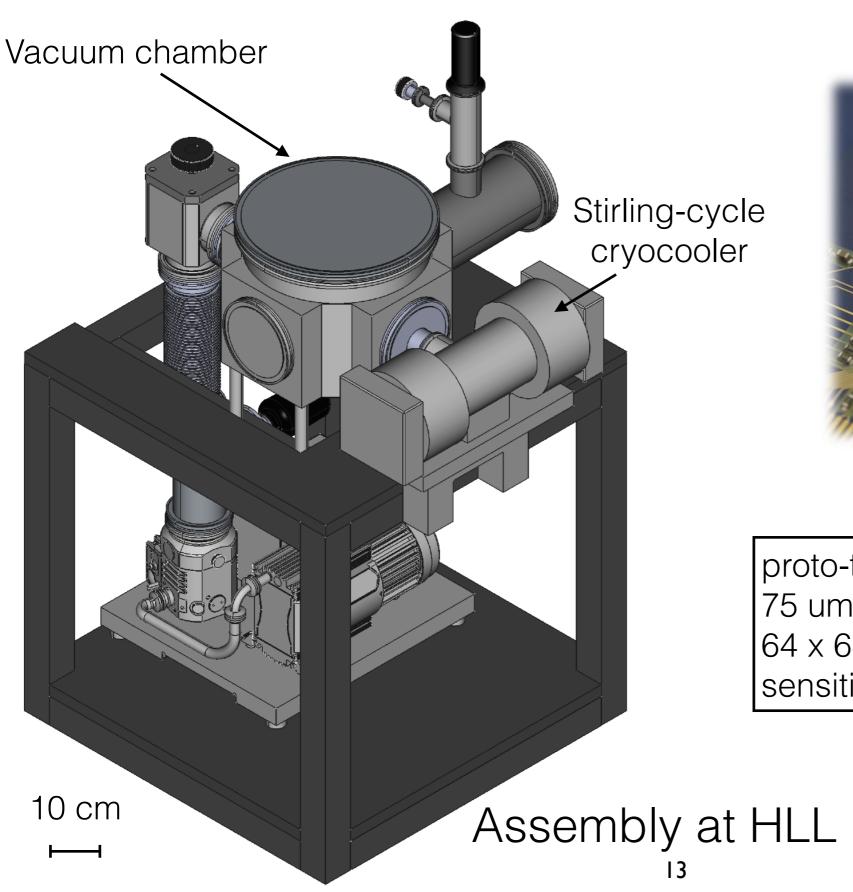


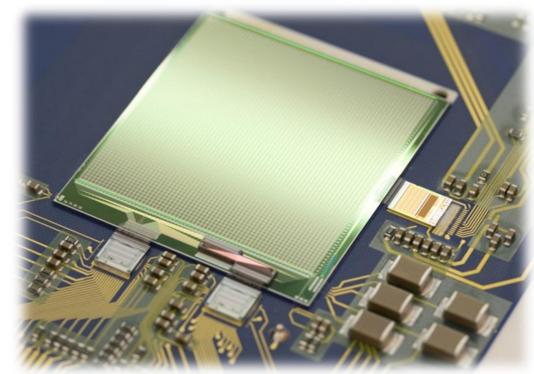
single pixel RNDR DEPFET effective noise:

0.2 e<sup>-</sup> RMS at 200 K

capable of distinguish single electron charge

# **DANAE** prototype test setup





Detector prototype at HLL-MPG courtesy of J. Treis

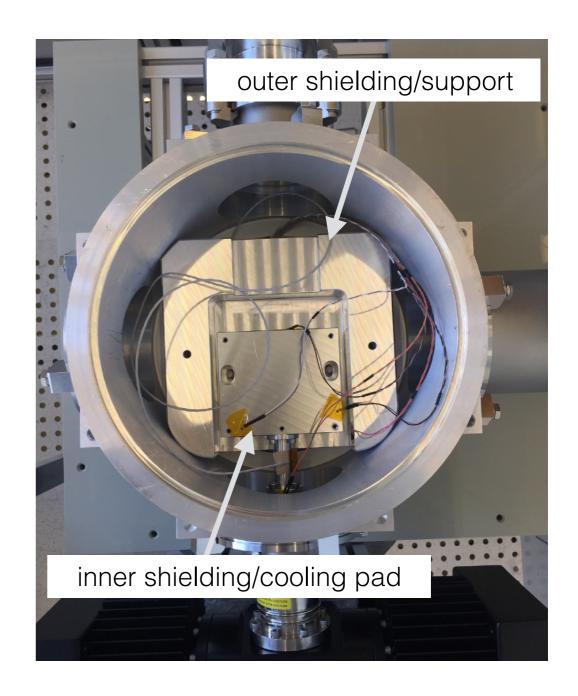
#### proto-type:

75 um x 75 um x 450 um single pixel, 64 x 64 matrix

sensitive volume **0.024** g

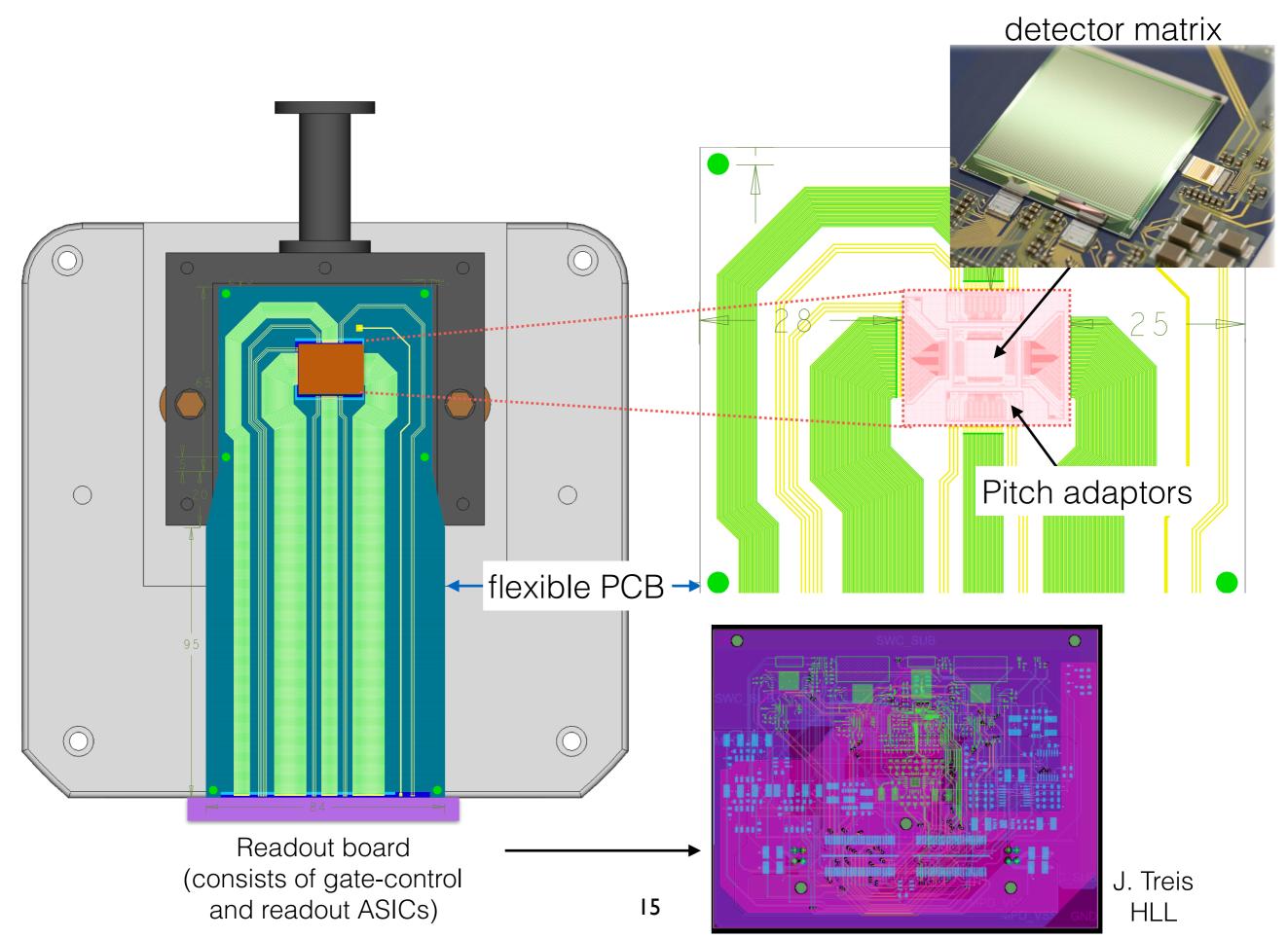
# Setup at HLL



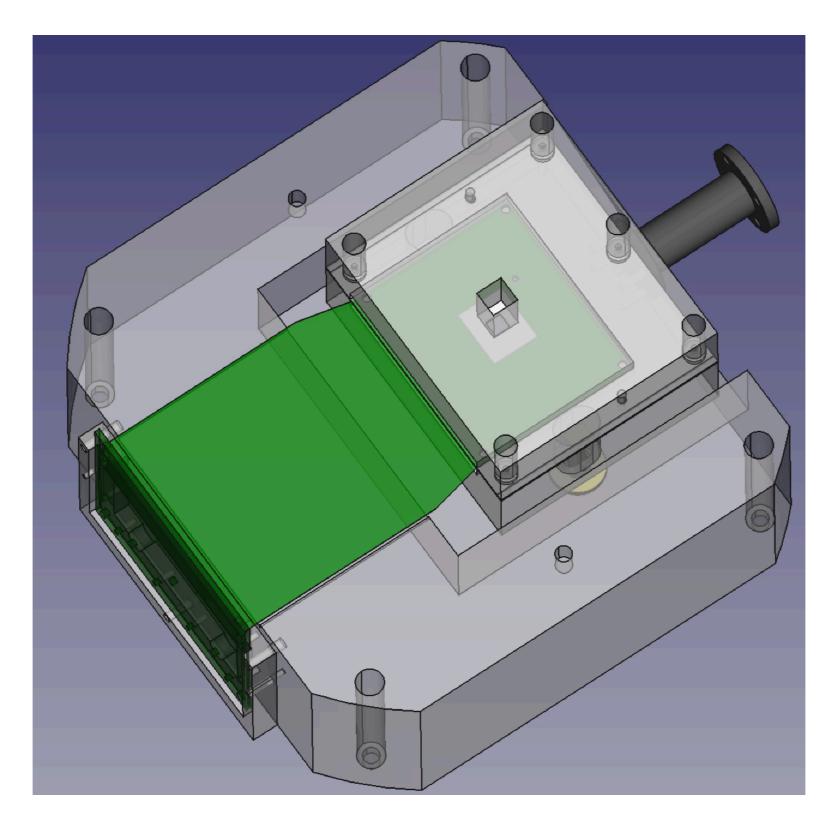


Vacuum and cooling test in March 2018 cooling pad reached 150 K

#### **Detector control and readout electronics**



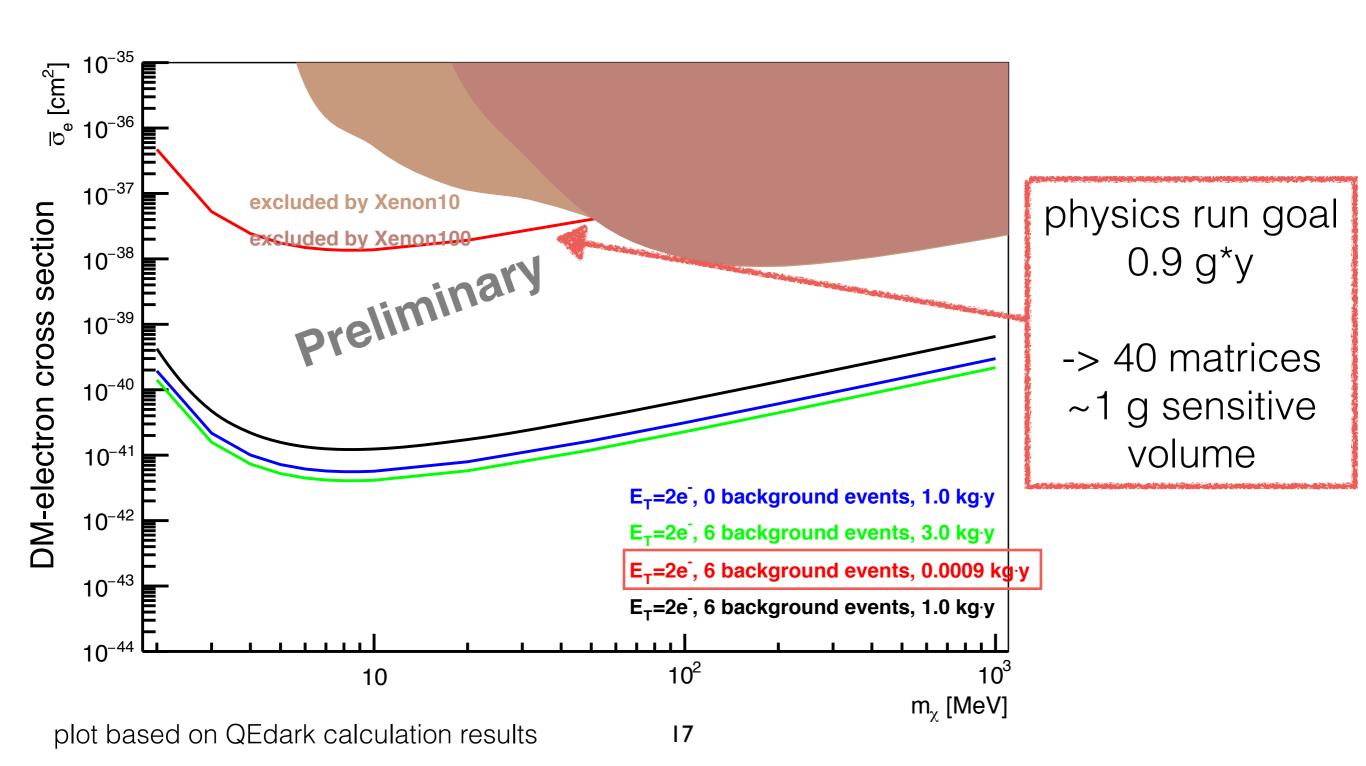
# Image of the detector assembly



To be assembled in July-August 2018

#### Physics run perspective

- Expect preliminary results from the prototype setup (0.024 g sensitive volume) in late 2018
- physics run with significant result requires more matrices



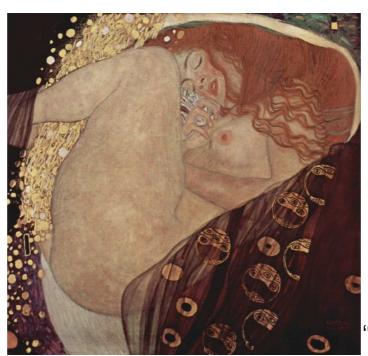
#### Summary

- sub *e* ENC low noise semiconductor detector capable of detecting the energy deposit from sub-GeV DM-electron recoil;
- DANAE prototype for test-of-principle measurement with 64 x 64 pixel matrix in preparation;
- one of the <u>first generation</u> experiments using non-destructive repetitive readout method.

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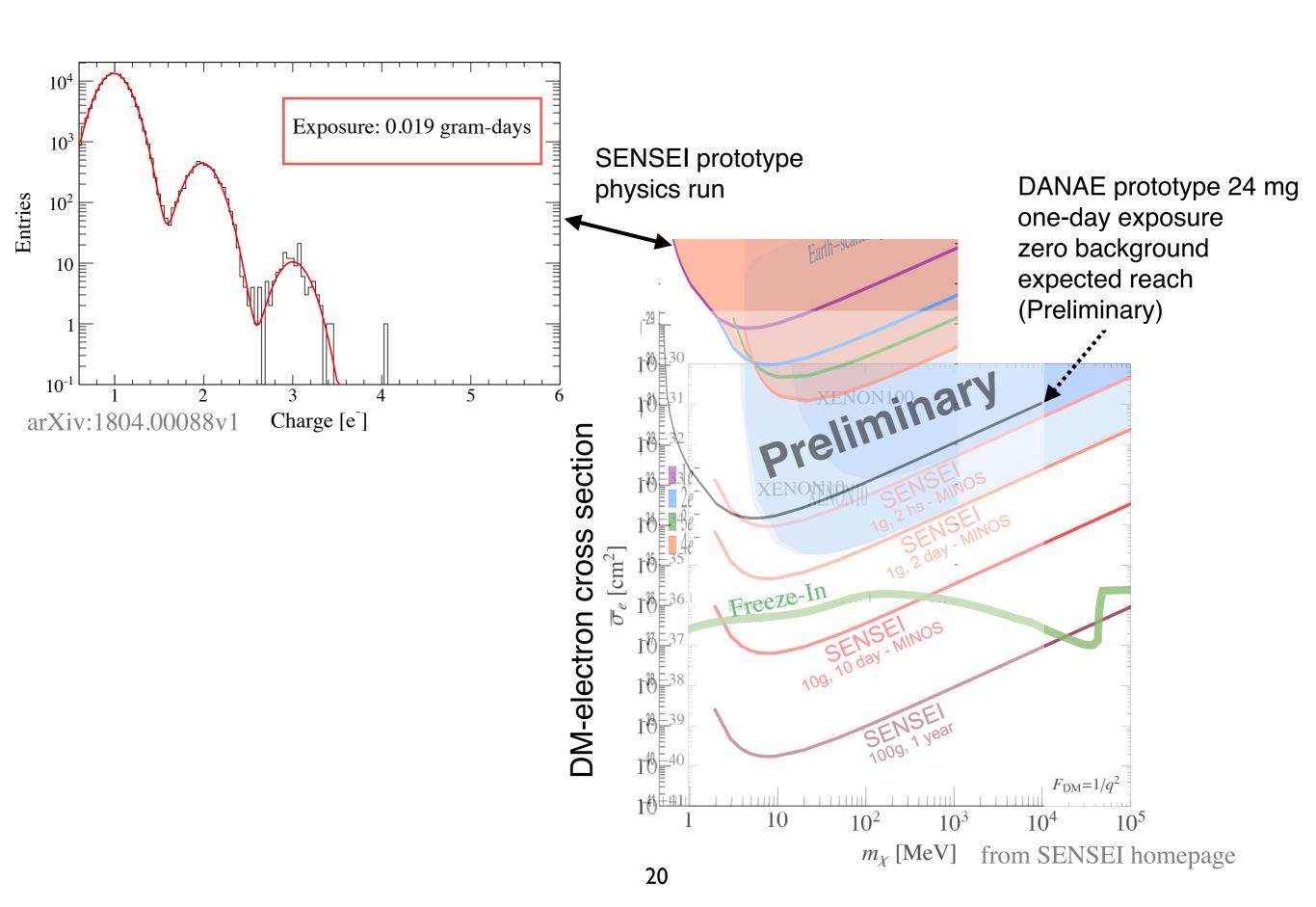


Germany

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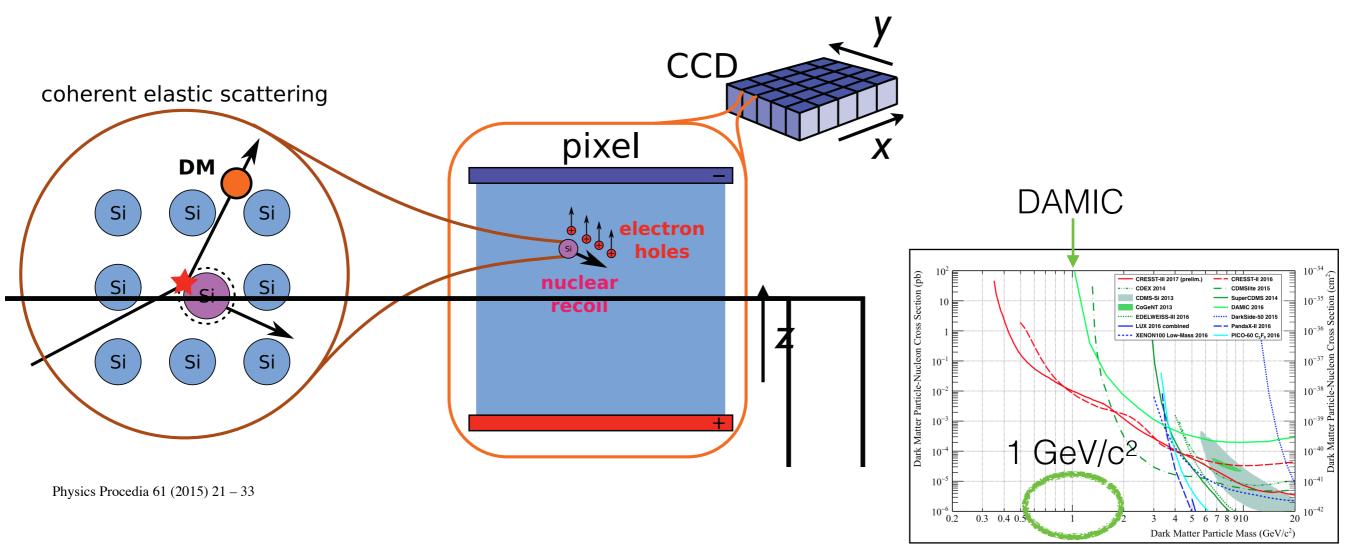
# **Expected 1day exposure compared to SENSEI**



#### **Application of Silicon detector**

DAMIC

**nucleus** recoil CCD, with physics results

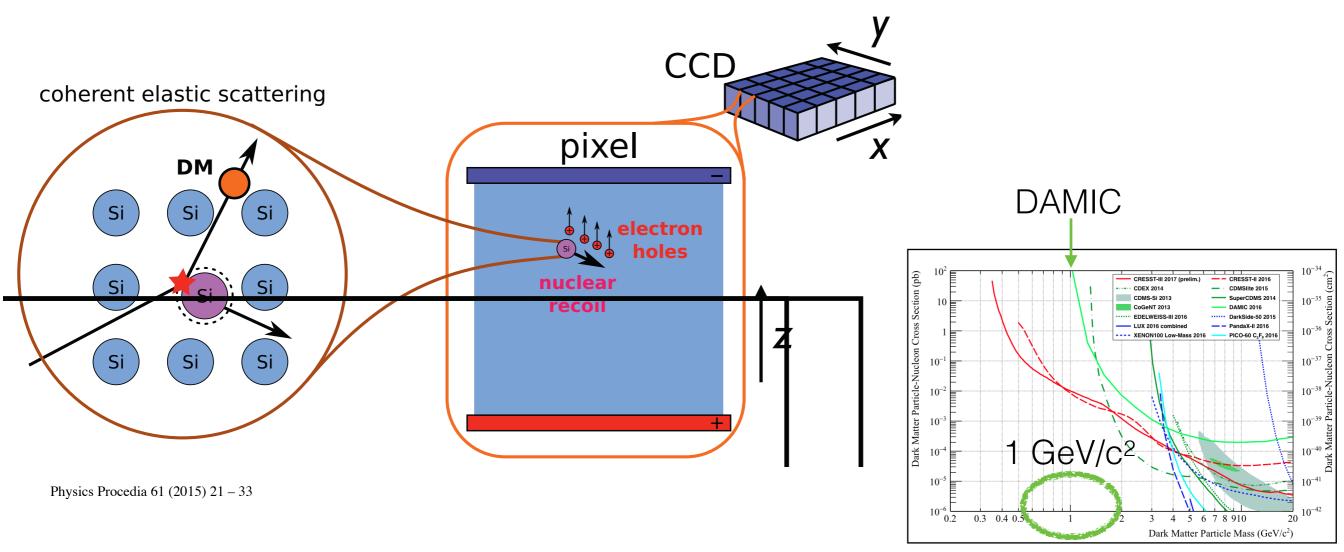


Readout noise determines threshold of ~ 11 e<sup>-</sup> (or ~ 40 eV)

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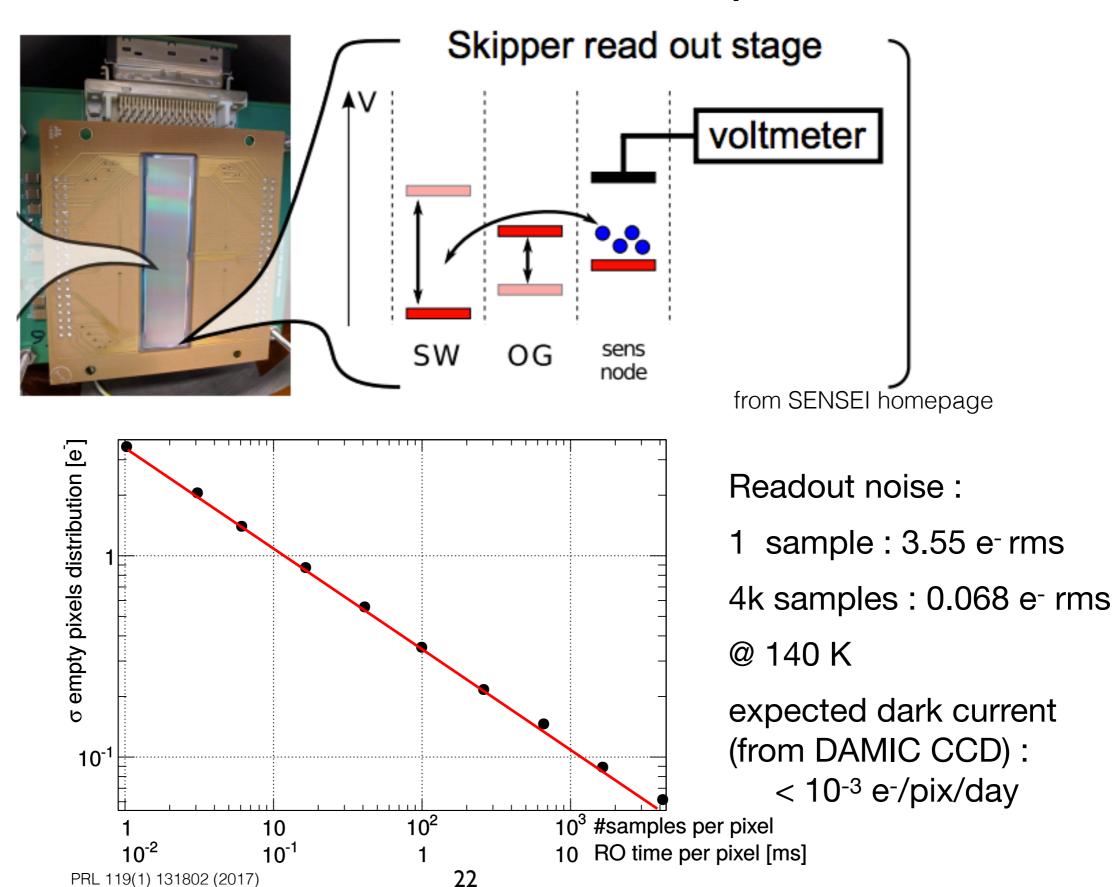


Readout noise determines threshold of ~ 11 e<sup>-</sup> (or ~ 40 eV)

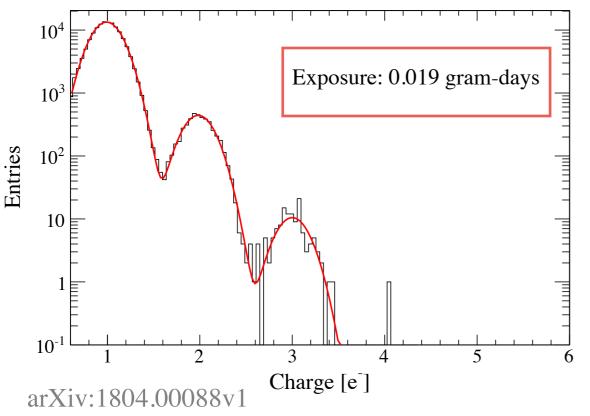
For O(MeV) DM-electron scattering, required threshold : O(e-) Sub-electron noise level necessary

#### **Skipper CCD for SENSEI**

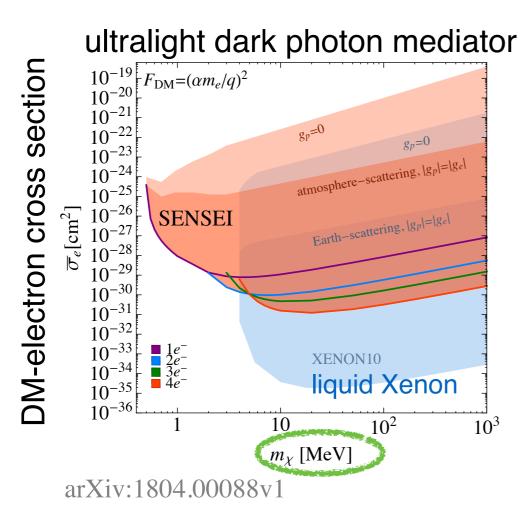
DAMIC CCD with **repetitive readout** 

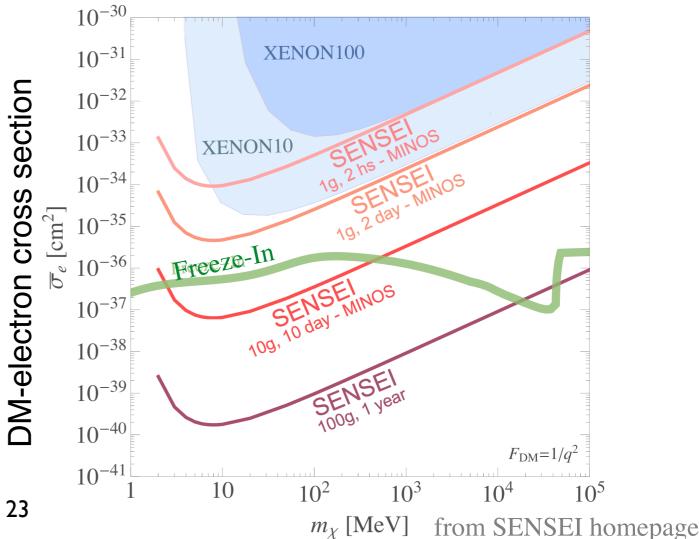


# SENSEI first result with "skipper" CCD

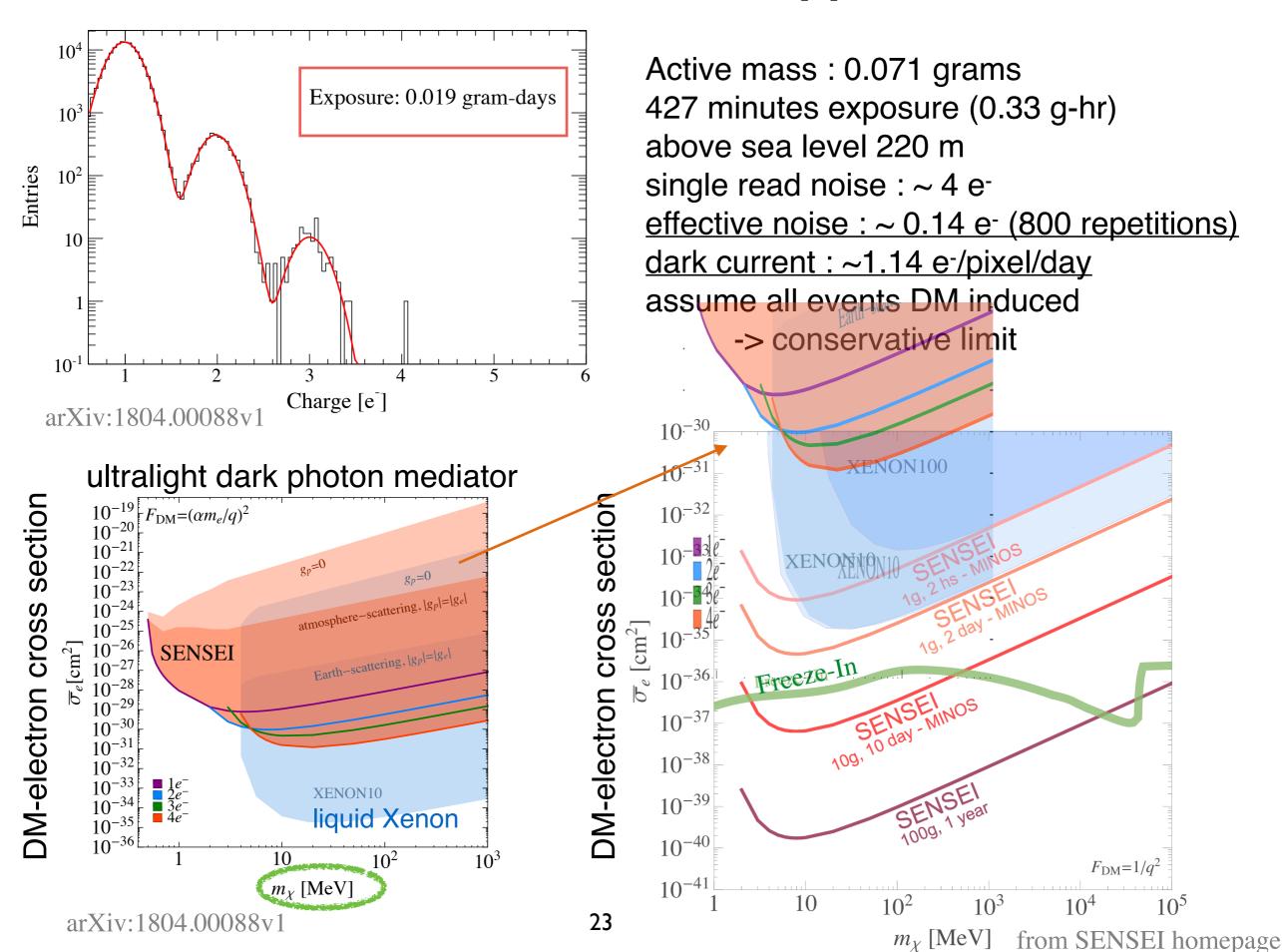


Active mass: 0.071 grams
427 minutes exposure (0.33 g-hr)
above sea level 220 m
single read noise: ~ 4 eeffective noise: ~ 0.14 e- (800 repetitions)
dark current: ~1.14 e-/pixel/day
assume all events DM induced
-> conservative limit





# SENSEI first result with "skipper" CCD



# A comparison with skipper CCD

Type	Pixel format [µm]	prototype mass	operating temp	dark current	readout time (1sample)	readout noise (optimal)
skipper CCD	15 x 15 x 200	0.071 g	140 K	< ~1.14 e-/pix/day	10 µs/pix/ amplifier	0.068 e-rms/pix
RNDR DEPFET	75 x 75 x 450	0.024 g	≈ 200 K	< <u>1</u> e-/pix/day	4 μs/ 64 pix	0.2 e-rms/pix

similar concepts of non-destructive readout, compatible performance; different architecture, different systematics;

-> good complementary from experimental point of view

RNDR: repetitive non-destructive readout

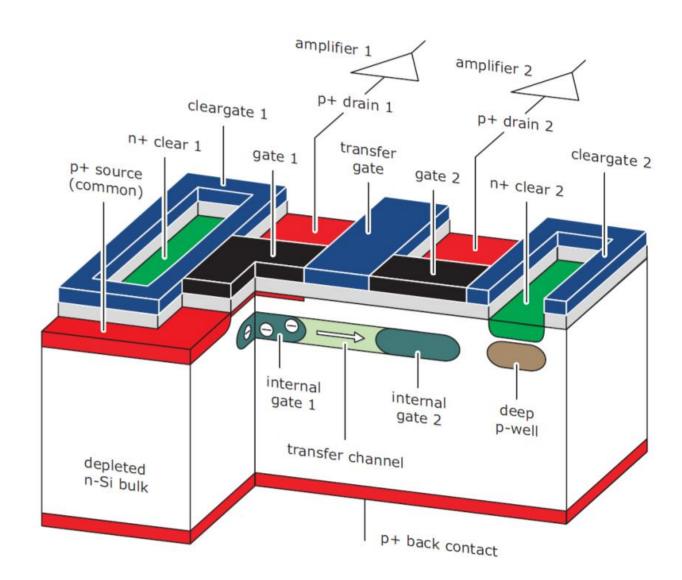
structure of a basic DEPFET cell: a "subpixel"

gate source drain bulk internal (00) gate DM back contact

EPJ C, 77(12), 279 (2017)

fully-depleted n-Si

structure of RNDR DEPFET "super-pixel"



EPJ C, 77(12), 279 (2017)

# **Cooling & shielding layout**

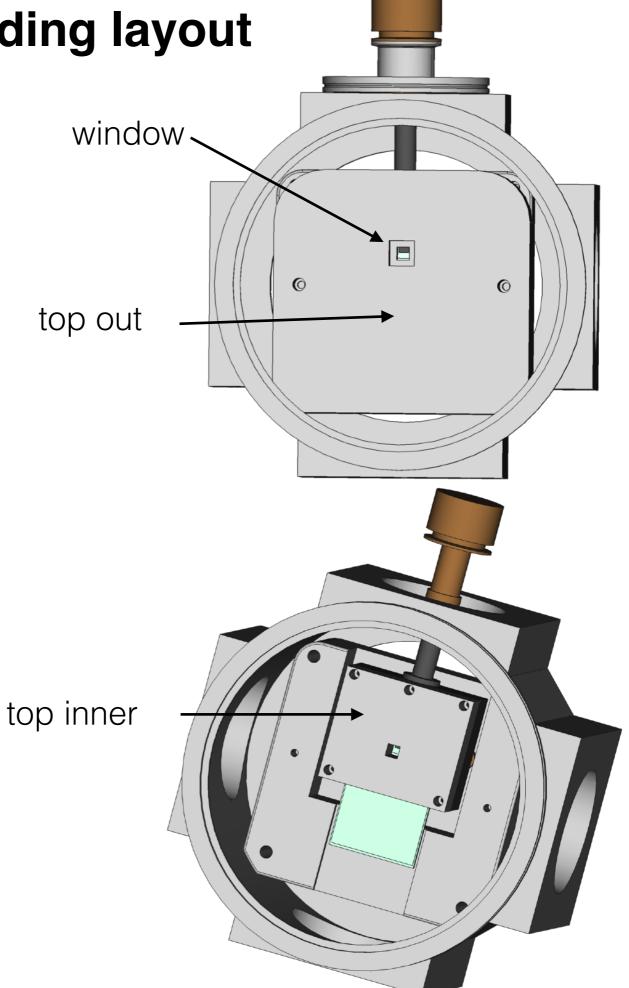
top-out



bot-out

outer shielding: support structure

inner shielding: cooling contact



#### **DEPFET matrix control & readout electronics**

#### **Detector** matrix

Front-end ASICS for the 64x64 matrix with interface to Switcher-S, VERITAS

#### Switcher-S

#### 64x2 channel analog multiplexer

Readout board

switcher id	W	N	Е	
function	Gate 1 & 2	Gate common	clear & transfer gate	
Voltage [V]	-2.5 ~ + 5	-0.5 ~ +20	-0.5 ~ + 20/25	

#### **VERITAS**

- VERITAS 2.1 ASIC in the AMS 0.35 µm CMOS 3.3 V technology
- 64 analog readout channels able to process in parallel the signals coming from 64 DEPFET devices.

#### **ADC**

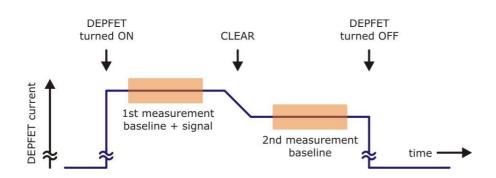
FADC type digitizer

#### **DEPFET CDS circle**

#### Detector Structures – Matrix Devices



#### → readout sequence

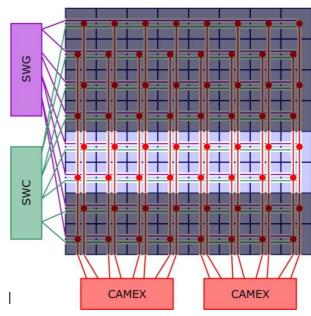


#### **Correlated double sampling:**

1st measurement: signal + baseline clear: removal of signal charges 2nd measurement: baseline

difference = signal
complete clear is mandatory!

#### matrix operation



vertical signal lines

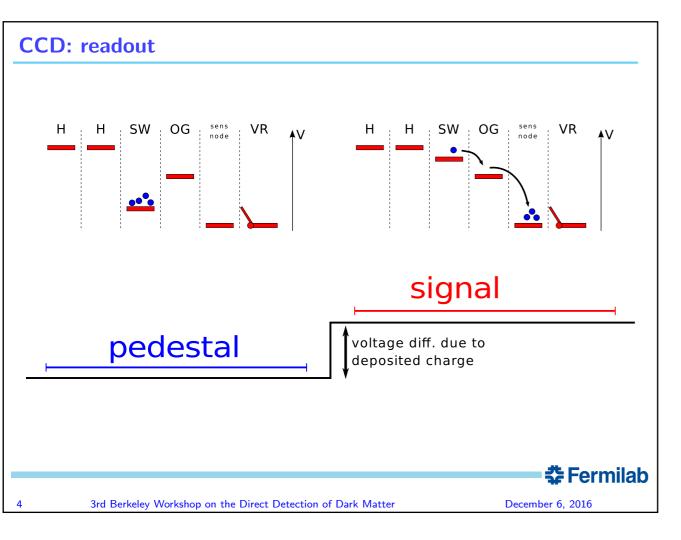
1 active row, other pixels integrating

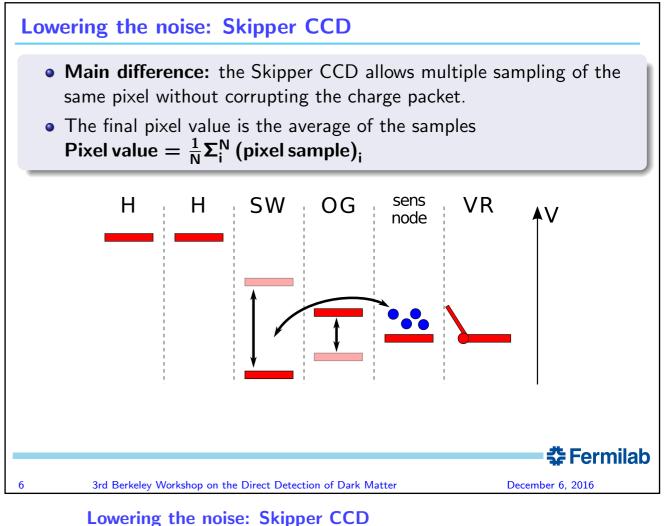
#### option to speed up (1)

readout parallelisation
2 x readout channels, 2 active rows

Johannes Treis / Halbleiterlabor der MPG

#### CCD (skipper) readout





• Main difference: the Skipper CCD allows multiple sampling of the

same pixel without corrupting the charge packet.

• The final pixel value is the average of the samples

Regular CCD

Pixel value =  $\frac{1}{N} \Sigma_{i}^{N}$  (pixel sample)

#### CCD: readout

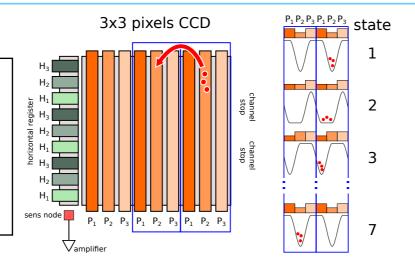
SW: summing-well gate

OG : output gate

**Javier Tiffenberg** 

RG: reset gate

VR: V\_ref



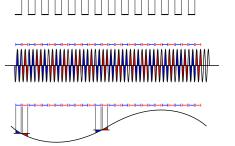
capacitance of the system is set by the SN: C=0.05pF ightarrow 3 $\mu$ V/e

# high frequency noise low frequency

pixel charge

measurement

noise

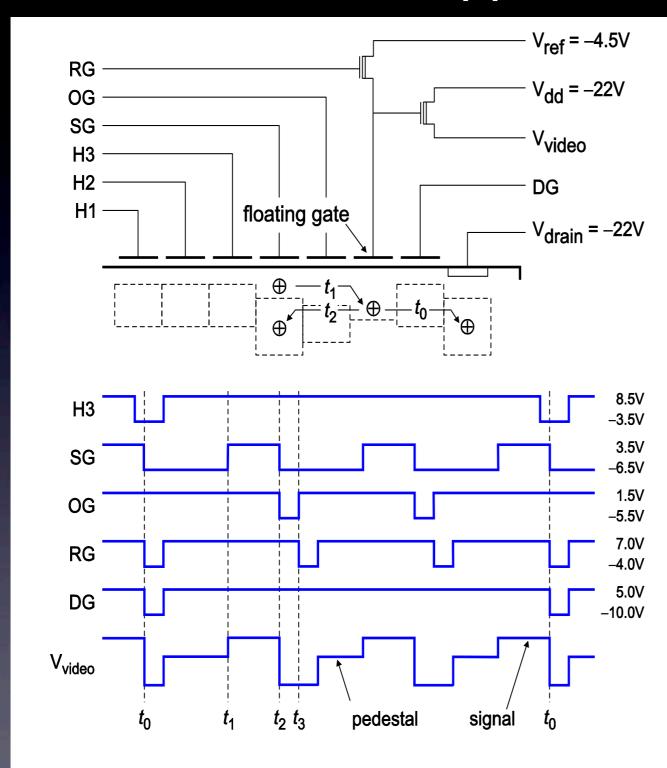


Skipper CCD



**♣** Fermilab

# Skipper CCD



The "skipper" allow multiple readouts of the charge in each pixel.

- Floating gate output instead of floating diffusion output used in regular CCDs.
- The charge can be moved back and forth between

Each readout integration time is kept short to make 1/f noise negligible.

A noise reduction of 1/sqrt(N) is achieved for N reads.

The total readout time per pixel increases linearly with N.